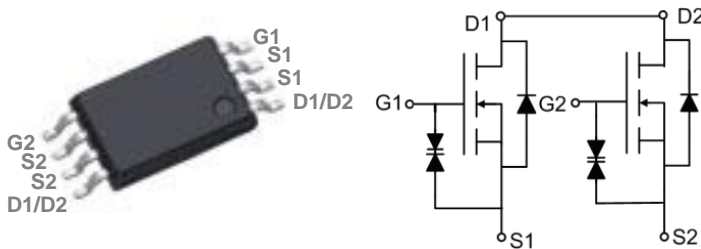


**General Description**

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

**TSSOP8 Dual Pin Configuration**



BVDSS	RDSON	ID
20V	9mΩ	10A

**Features**

- 20V, 10A,  $R_{DS(ON)}=9m\Omega@V_{GS}=4.5V$
- Improved  $dv/dt$  capability
- Fast switching
- Green Device Available
- Suit for 1.8V Gate Drive Applications

**Applications**

- Notebook
- Load Switch
- LED applications

**Absolute Maximum Ratings**  $T_c=25^\circ C$  unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	20	V
$V_{GS}$	Gate-Source Voltage	$\pm 10$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ C$ )	10	A
	Drain Current – Continuous ( $T_c=100^\circ C$ )	6.3	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	40	A
$P_D$	Power Dissipation ( $T_c=25^\circ C$ )	1.25	W
	Power Dissipation – Derate above $25^\circ C$	0.01	W/ $^\circ C$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

**Thermal Characteristics**

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	100	$^\circ C/W$

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	20	---	---	V
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =1mA	---	0.01	---	V/°C
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =16V, V <sub>GS</sub> =0V, T <sub>J</sub> =125°C	---	---	10	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±10V, V <sub>DS</sub> =0V	---	---	±100	nA

**On Characteristics**

R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =4.5V, I <sub>D</sub> =6A	---	---	9	mΩ
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =4A	---	---	10	
		V <sub>GS</sub> =1.8V, I <sub>D</sub> =2A	---	---	11.5	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	0.3	0.6	1	V
ΔV <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient		---	2	---	mV/°C
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =10V, I <sub>S</sub> =5A	---	20	---	S

**Dynamic and switching Characteristics**

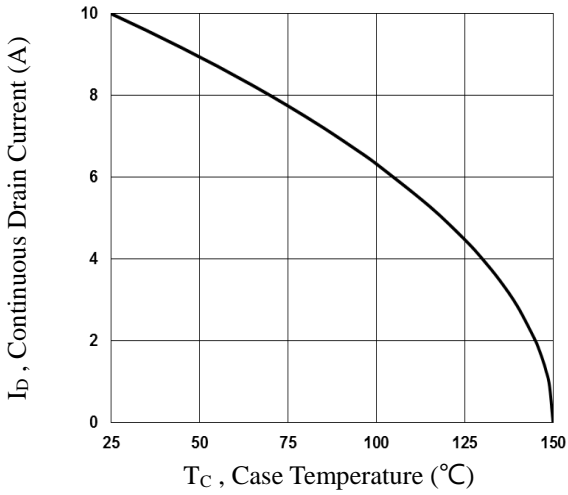
Q <sub>g</sub>	Total Gate Charge <sup>2, 3</sup>	V <sub>DS</sub> =10V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =6A	---	29.8	45	nC
Q <sub>gs</sub>	Gate-Source Charge <sup>2, 3</sup>		---	2.7	6	
Q <sub>gd</sub>	Gate-Drain Charge <sup>2, 3</sup>		---	9	14	
T <sub>d(on)</sub>	Turn-On Delay Time <sup>2, 3</sup>	V <sub>DD</sub> =10V, V <sub>GS</sub> =4.5V, R <sub>G</sub> =25Ω I <sub>D</sub> =1A	---	13.5	26	nS
T <sub>r</sub>	Rise Time <sup>2, 3</sup>		---	29	55	
T <sub>d(off)</sub>	Turn-Off Delay Time <sup>2, 3</sup>		---	66.9	127	
T <sub>f</sub>	Fall Time <sup>2, 3</sup>		---	19.2	36	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =10V, V <sub>GS</sub> =0V, F=1MHz	---	1920	2790	pF
C <sub>oss</sub>	Output Capacitance		---	280	410	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	180	270	

**Drain-Source Diode Characteristics and Maximum Ratings**

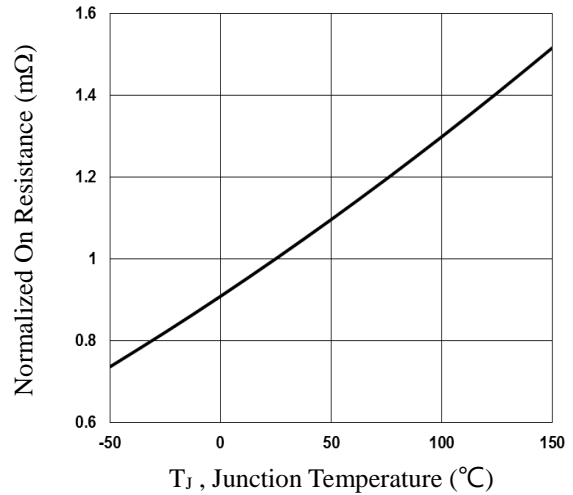
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	10	A
I <sub>SM</sub>	Pulsed Source Current		---	---	40	A
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =1A, T <sub>J</sub> =25°C	---	---	1	V

Note :

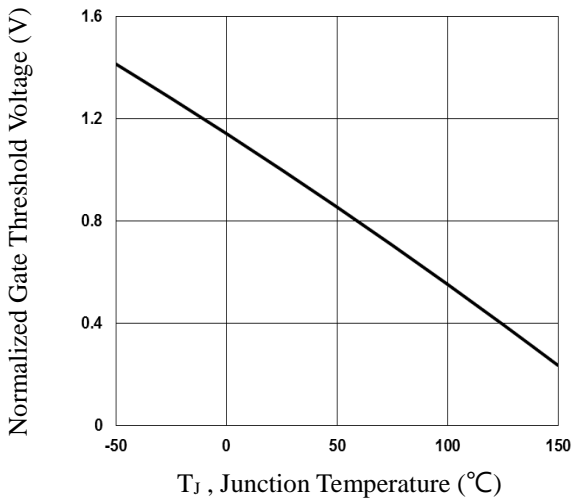
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
3. Essentially independent of operating temperature.



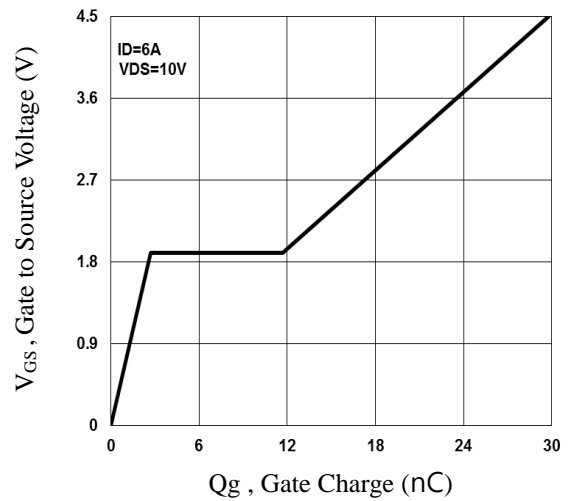
**Fig.1 Continuous Drain Current vs. T<sub>c</sub>**



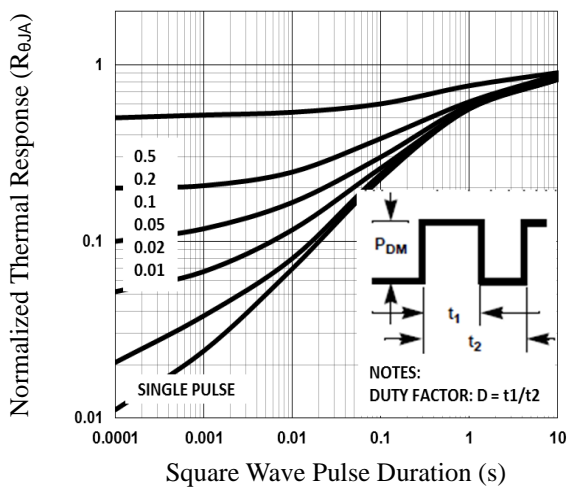
**Fig.2 Normalized R<sub>DS(on)</sub> vs. T<sub>j</sub>**



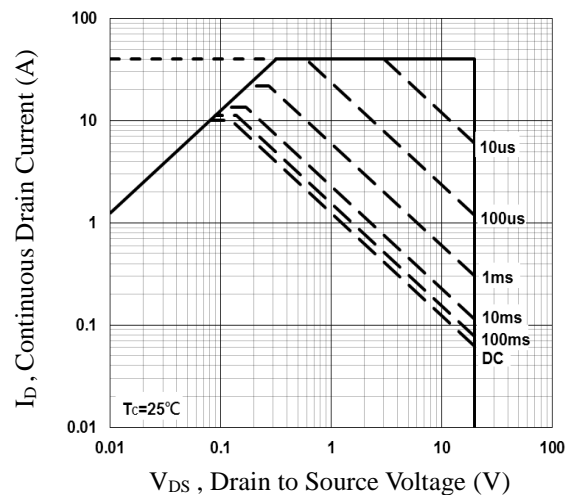
**Fig.3 Normalized V<sub>th</sub> vs. T<sub>j</sub>**



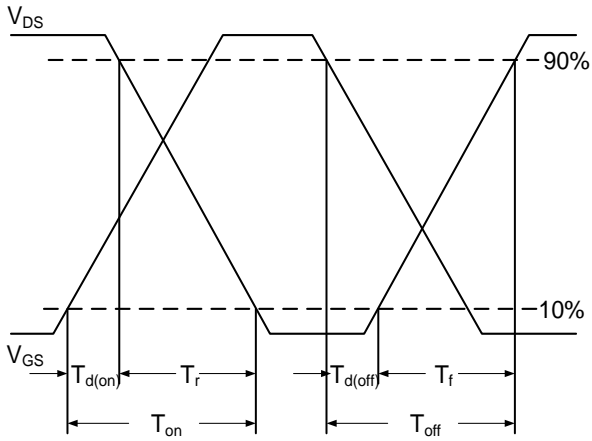
**Fig.4 Gate Charge Waveform**



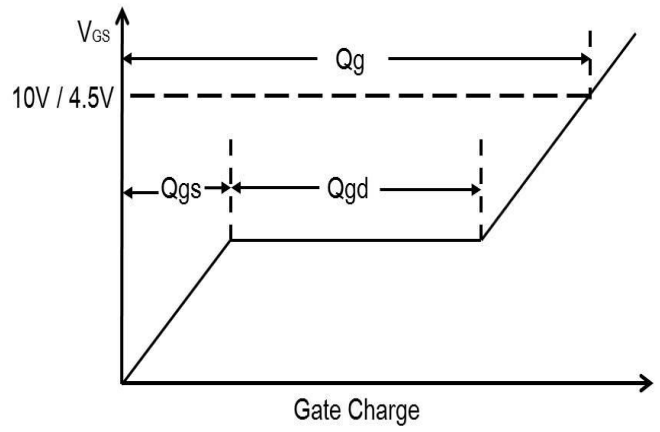
**Fig.5 Normalized Transient Impedance**



**Fig.6 Maximum Safe Operation Area**

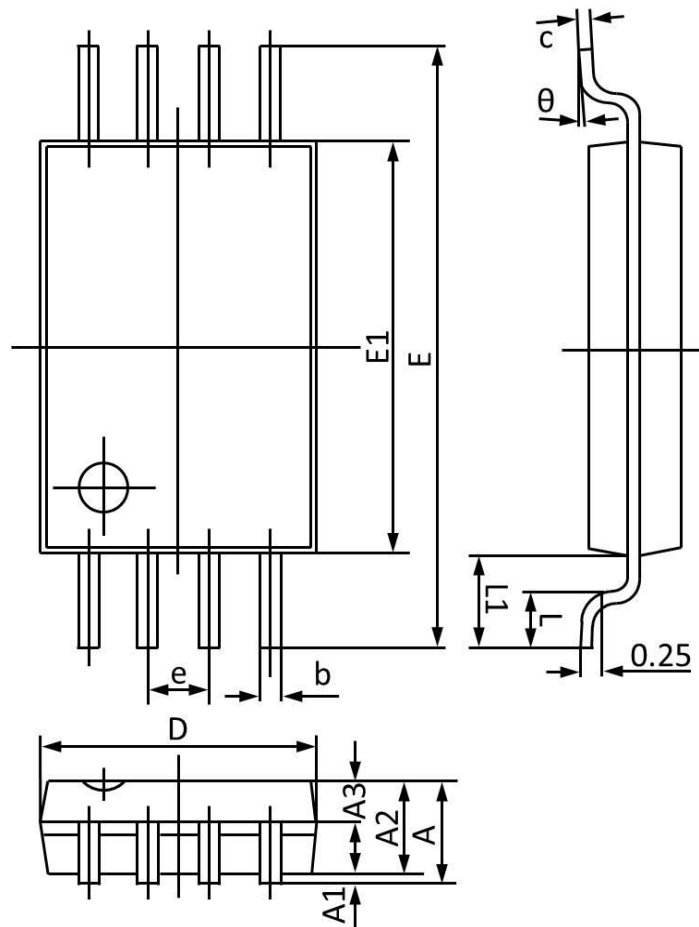


**Fig.7 Switching Time Waveform**



**Fig.8 Gate Charge Waveform**

## TSSOP8 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.100	1.200	0.044	0.047
A1	0.050	0.150	0.002	0.006
A2	0.900	1.050	0.036	0.041
A3	0.390	0.490	0.016	0.019
b	0.210	0.300	0.009	0.011
c	0.130	0.190	0.006	0.007
D	2.900	3.100	0.114	0.122
E	6.200	6.600	0.244	0.260
E1	4.300	4.500	0.169	0.177
e	0.650(BSC)		0.025(BSC)	
L	0.450	0.750	0.018	0.029
L1	1.000(BSC)		0.039(BSC)	
$\theta$	0°	8°	0°	8°